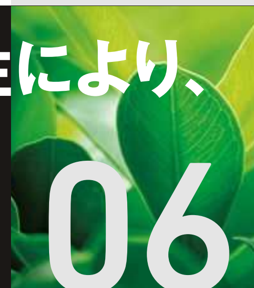
微細なパターン形成と優れた絶縁信頼性により、パッケージ基板の高密度化に貢献

Fine pattern formation and excellent insulation reliability contribute to high-density package substrates



感光性層間絶縁材料
PVI-3 HR100S

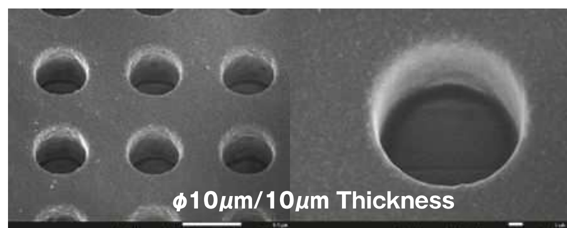
Photo Imageable Dielectric Material

特　長 Features

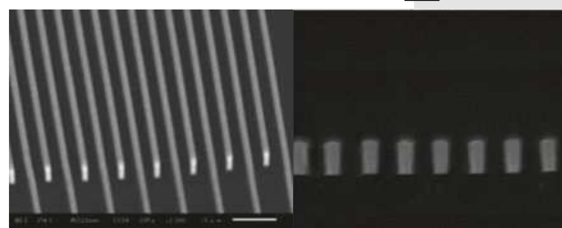
- **高解像性** Smaller Via opening
- **高絶縁信頼性** High insulation reliability
- **ドライフィルムタイプ** Dry Film type
- **低温硬化** Low Curing Temperature (180deg.C)

特　性 Properties

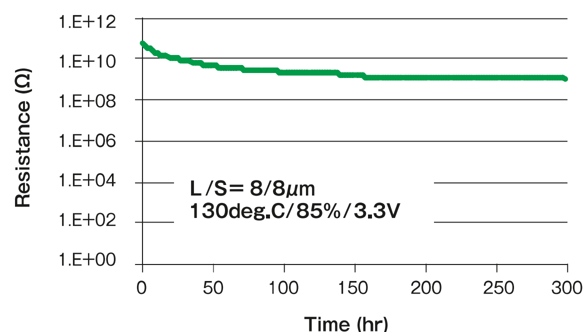
Resolution



2μm Line on PID



Insulation (BHAST between lines)



Properties

Tg (TMA)	deg.C	180-185
CTE　α1	ppm	40-45
Young' Modulus	GPa	3.0-3.5
Tensile Strength	MPa	75-80
Elongation	%	12-15
Residual Stress	MPa	22-24

用　途 Application

シリコン/ガラス/有機インターポーザ
Si/Glass/Organic Interposer

ウエハレベルパッケージ
WLP

パネルレベルパッケージ
PLP